



# PMEG3002AELD

30 V, 0.2 A low  $V_F$  MEGA Schottky barrier rectifier

Rev. 1 — 19 April 2011

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

### 1.2 Features and benefits

- Forward current:  $I_F \leq 0.2$  A
- Reverse voltage:  $V_R \leq 30$  V
- Low forward voltage:  $V_F \leq 480$  mV
- Ultra small and leadless SMD plastic package
- AEC-Q101 qualified
- Solderable side pads
- Package height typ. 0.37 mm

### 1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications
- Ultra high-speed switching

### 1.4 Quick reference data

Table 1. Quick reference data

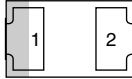

| Symbol      | Parameter               | Conditions                                 | Min | Typ | Max | Unit    |    |
|-------------|-------------------------|--|-----|-----|-----|---------|----|
| $I_{F(AV)}$ | average forward current | square wave; $\delta = 0.5$ ; $f = 20$ kHz |     |     |     |         |    |
|             |                         | $T_{amb} \leq 125$ °C                      | [1] | -   | -   | 0.2     | A  |
|             |                         | $T_{sp} \leq 140$ °C                       | -   | -   | -   | 0.2     | A  |
| $I_R$       | reverse current         | $V_R = 10$ V                               | -   | 3.5 | 10  | $\mu$ A |    |
| $V_R$       | reverse voltage         |  | -   | -   | 30  | V       |    |
| $V_F$       | forward voltage         | $I_F = 200$ mA                             | [2] | -   | 430 | 480     | mV |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

[2] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

Table 2. Pinning

| Pin | Description | Simplified outline  | Graphic symbol  |
|-----|-------------|---|---|
| 1   | cathode     |  <p>Transparent top view</p> |  <p>sym001</p> |
| 2   | anode       |   |   |

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 3. Ordering information

| Type number  | Package |  |         |
|--------------|---------|--|---------|
|              | Name    | Description  | Version |
| PMEG3002AELD | -       | leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm | SOD882D |

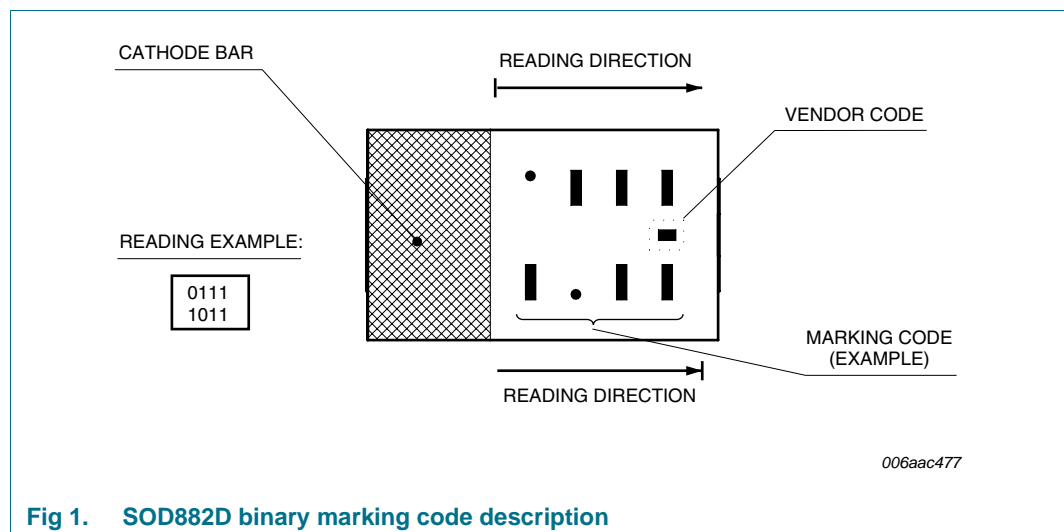
## 4. Marking

Table 4. Marking codes

| Type number  | Marking code <sup>[1]</sup> |
|--------------|-----------------------------|
| PMEG3002AELD | 1101 0000                   |

[1] For SOD882D binary marking code description, see [Figure 1](#).

### 4.1 Binary marking code description



## 5. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol      | Parameter                           | Conditions                                    | Min | Max  | Unit |    |
|-------------|-------------------------------------|---|-----|------|------|----|
| $V_R$       | reverse voltage                     |   | -   | 30   | V    |    |
| $I_{F(AV)}$ | average forward current             | square wave; $\delta = 0.5$ ;<br>$f = 20$ kHz |     |      |      |    |
|             |                                     | $T_{amb} \leq 125$ °C                         | [1] | -    | 0.2  | A  |
|             |                                     | $T_{sp} \leq 140$ °C                          |     | -    | 0.2  | A  |
| $I_{FRM}$   | repetitive peak forward current     | $t_p \leq 1$ ms; $\delta \leq 0.25$           | -   | 1    | A    |    |
| $I_{FSM}$   | non-repetitive peak forward current | square wave; $t_p = 8$ ms                     | [2] | -    | 3    | A  |
| $P_{tot}$   | total power dissipation             | $T_{amb} \leq 25$ °C                          | [3] | -    | 340  | mW |
|             |                                     |   | [1] | -    | 660  | mW |
|             |                                     |   | [4] | -    | 1000 | mW |
| $T_j$       | junction temperature                |   | -   | 150  | °C   |    |
| $T_{amb}$   | ambient temperature                 |   | -55 | +150 | °C   |    |
| $T_{stg}$   | storage temperature                 |   | -65 | +150 | °C   |    |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

[2]  $T_j = 25$  °C prior to surge.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

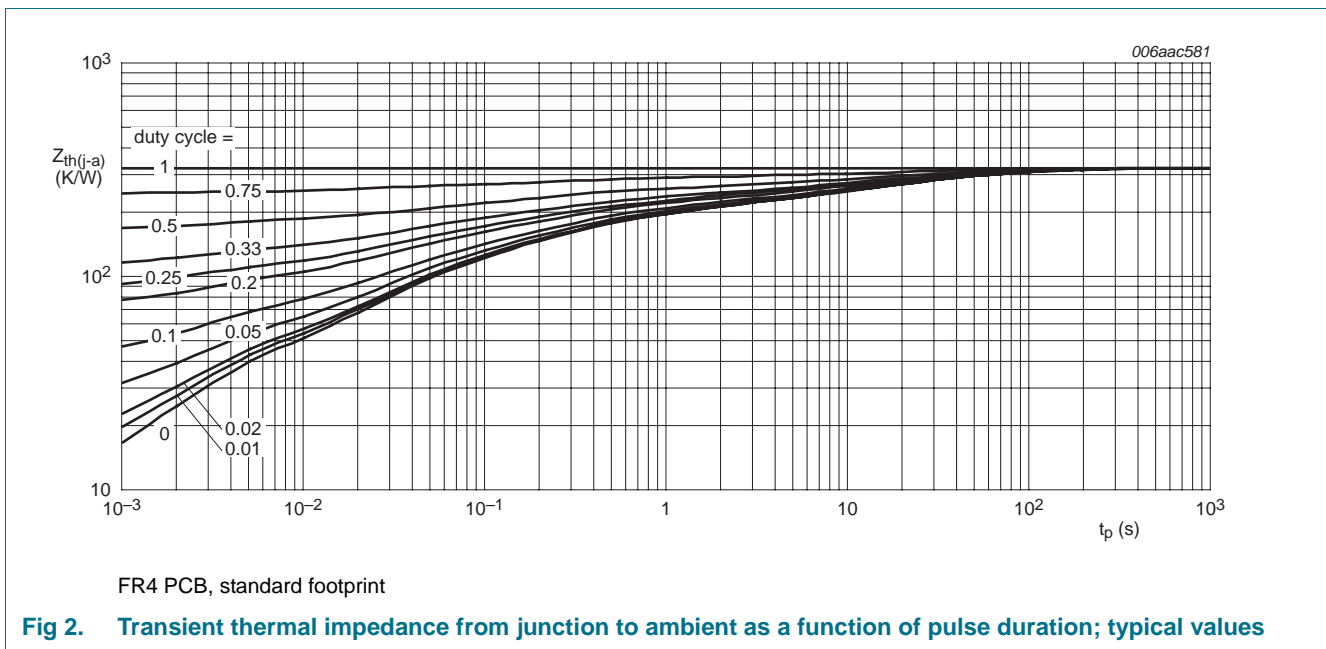
[4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

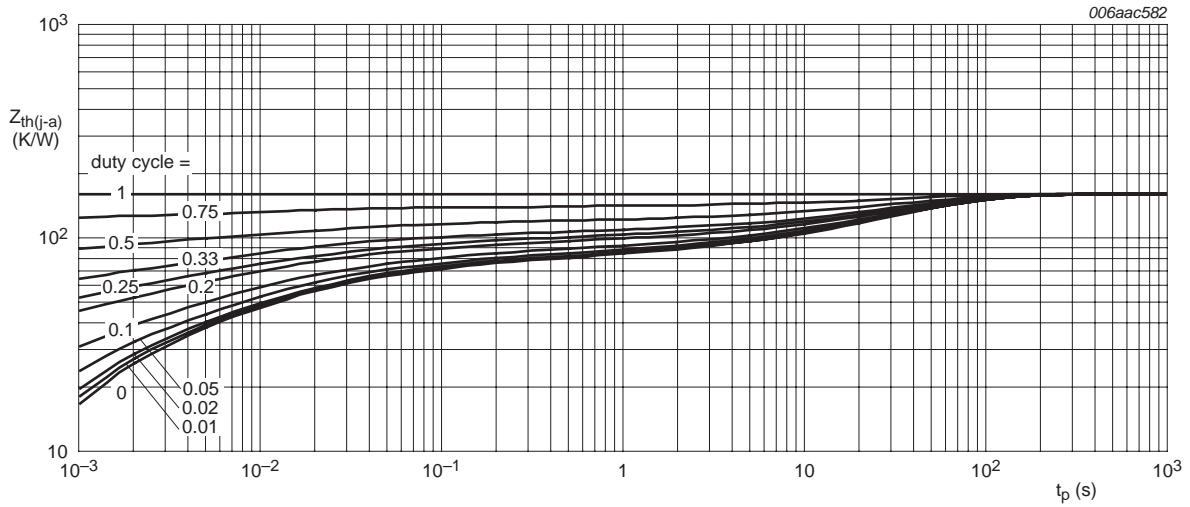
## 6. Thermal characteristics

**Table 6. Thermal characteristics**

| Symbol         | Parameter  | Conditions  | Min    | Typ | Max | Unit |     |
|----------------|--|-------------|--------|-----|-----|------|-----|
| $R_{th(j-a)}$  | thermal resistance from junction to ambient      | in free air | [1][2] | -   | -   | 370  | K/W |
|                |  |             | [1][3] | -   | -   | 190  | K/W |
|                |  |             | [1][4] | -   | -   | 125  | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point |             | [5]    | -   | 50  | K/W  |     |

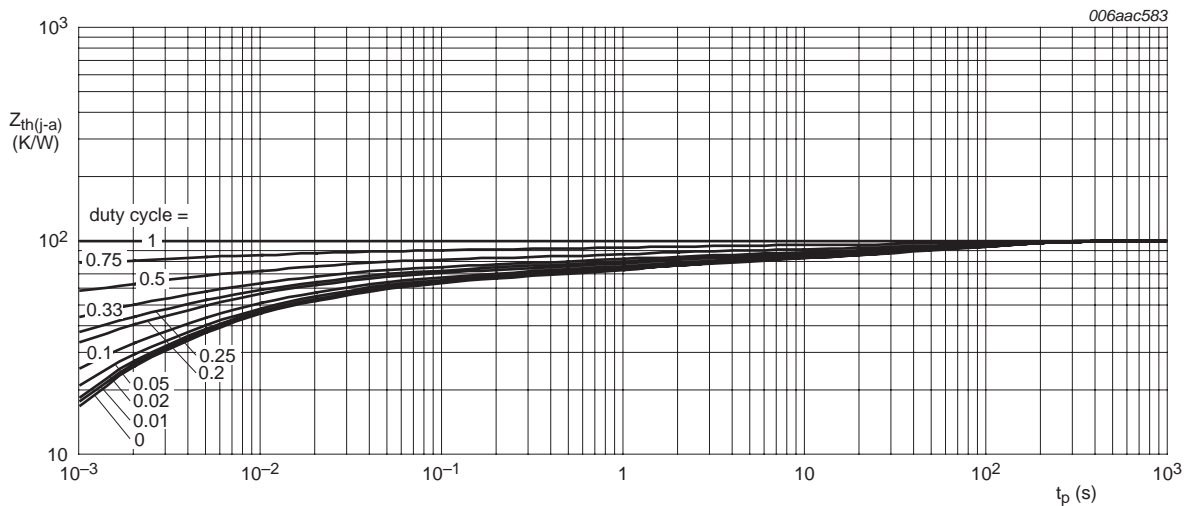
- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of cathode tab.





FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 7. Characteristics

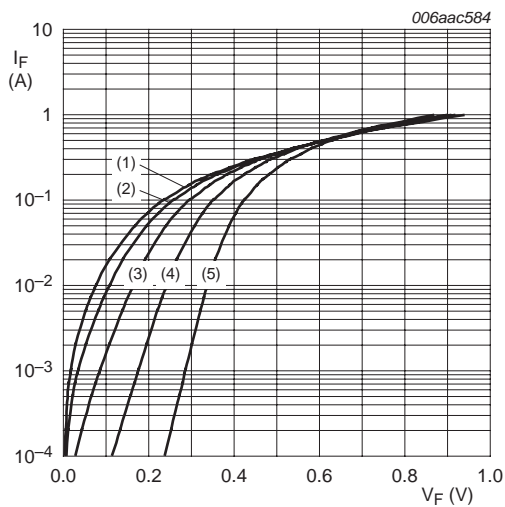
**Table 7. Characteristics**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

| Symbol   | Parameter             | Conditions                           | Min | Typ | Max | Unit          |
|----------|-----------------------|--------------------------------------|-----|-----|-----|---------------|
| $V_F$    | forward voltage       |                                      | [1] |     |     |               |
|          |                       | $I_F = 0.1\text{ mA}$                | -   | 120 | 190 | mV            |
|          |                       | $I_F = 1\text{ mA}$                  | -   | 180 | 250 | mV            |
|          |                       | $I_F = 10\text{ mA}$                 | -   | 250 | 300 | mV            |
|          |                       | $I_F = 100\text{ mA}$                | -   | 355 | 400 | mV            |
| $I_R$    | reverse current       | $V_R = 10\text{ V}$                  | -   | 3.5 | 10  | $\mu\text{A}$ |
|          |                       | $V_R = 30\text{ V}$                  | -   | 12  | 50  | $\mu\text{A}$ |
| $C_d$    | diode capacitance     | $V_R = 1\text{ V}; f = 1\text{ MHz}$ | -   | 18  | 25  | pF            |
| $t_{rr}$ | reverse recovery time |                                      | [2] | 6   | -   | ns            |

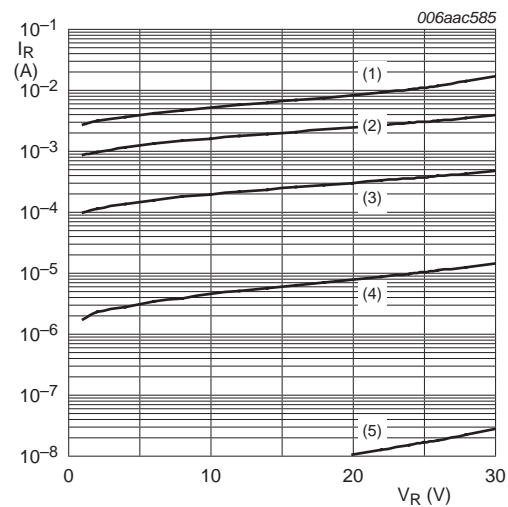
[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .

[2] When switched from  $I_F = 10\text{ mA}$  to  $I_R = 10\text{ mA}$ ;  $R_L = 100\text{ }\Omega$ ; measured at  $I_R = 1\text{ mA}$ .



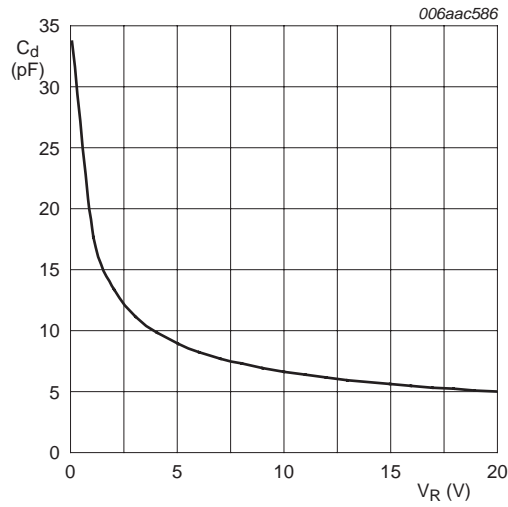
- (1)  $T_j = 150\text{ °C}$
- (2)  $T_j = 125\text{ °C}$
- (3)  $T_j = 85\text{ °C}$
- (4)  $T_j = 25\text{ °C}$
- (5)  $T_j = -40\text{ °C}$

**Fig 5. Forward current as a function of forward voltage; typical values**



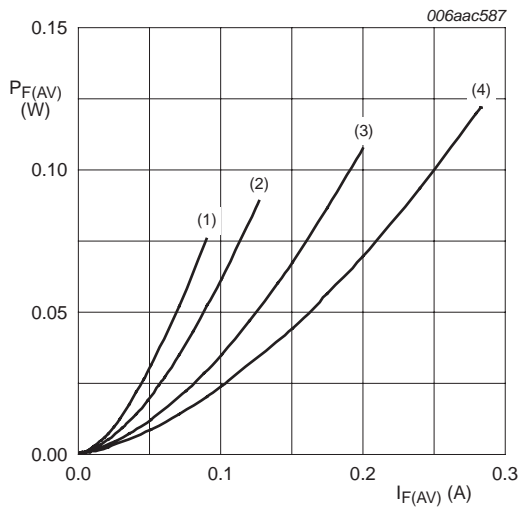
- (1)  $T_j = 150\text{ °C}$
- (2)  $T_j = 125\text{ °C}$
- (3)  $T_j = 85\text{ °C}$
- (4)  $T_j = 25\text{ °C}$
- (5)  $T_j = -40\text{ °C}$

**Fig 6. Reverse current as a function of reverse voltage; typical values**



$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

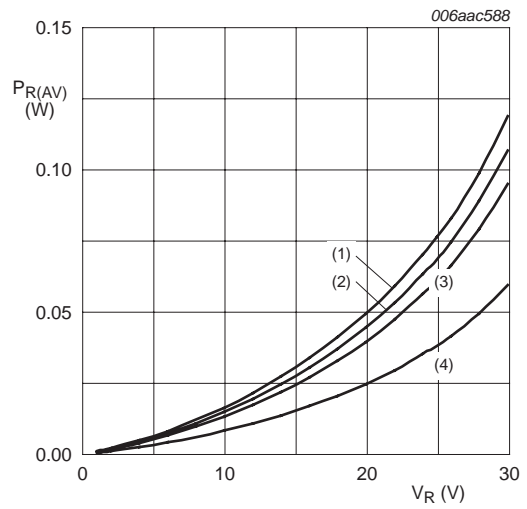
**Fig 7. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

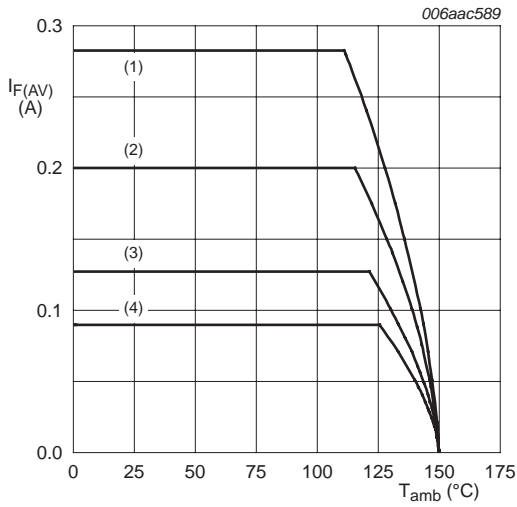
**Fig 8. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^\circ\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig 9. Average reverse power dissipation as a function of reverse voltage; typical values**

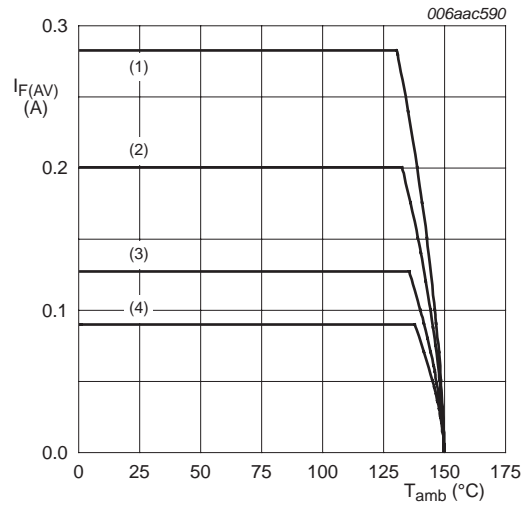


FR4 PCB, standard footprint

$T_j = 150\text{ °C}$

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 10. Average forward current as a function of ambient temperature; typical values**

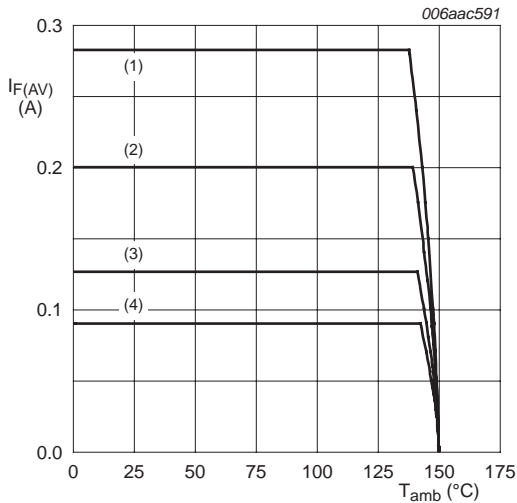


FR4 PCB, mounting pad for cathode  $1\text{ cm}^2$

$T_j = 150\text{ °C}$

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 11. Average forward current as a function of ambient temperature; typical values**

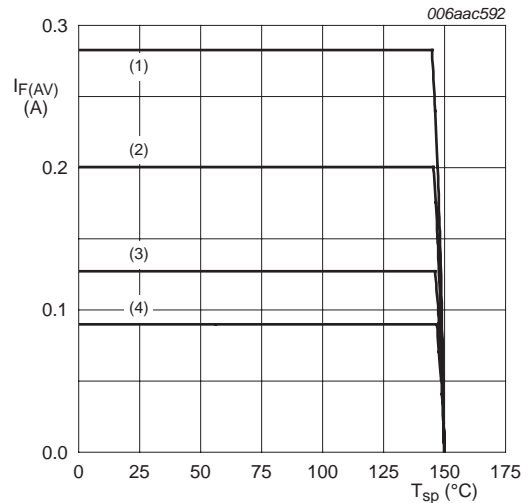


Ceramic PCB,  $\text{Al}_2\text{O}_3$ , standard footprint

$T_j = 150\text{ °C}$

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 12. Average forward current as a function of ambient temperature; typical values**



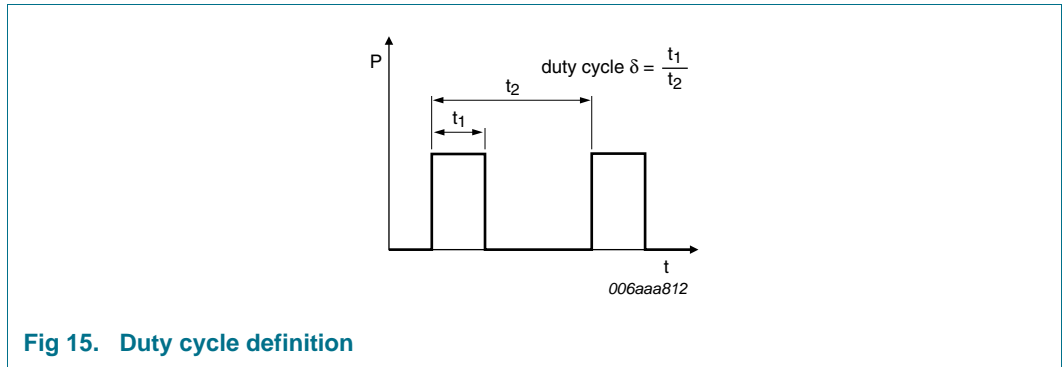
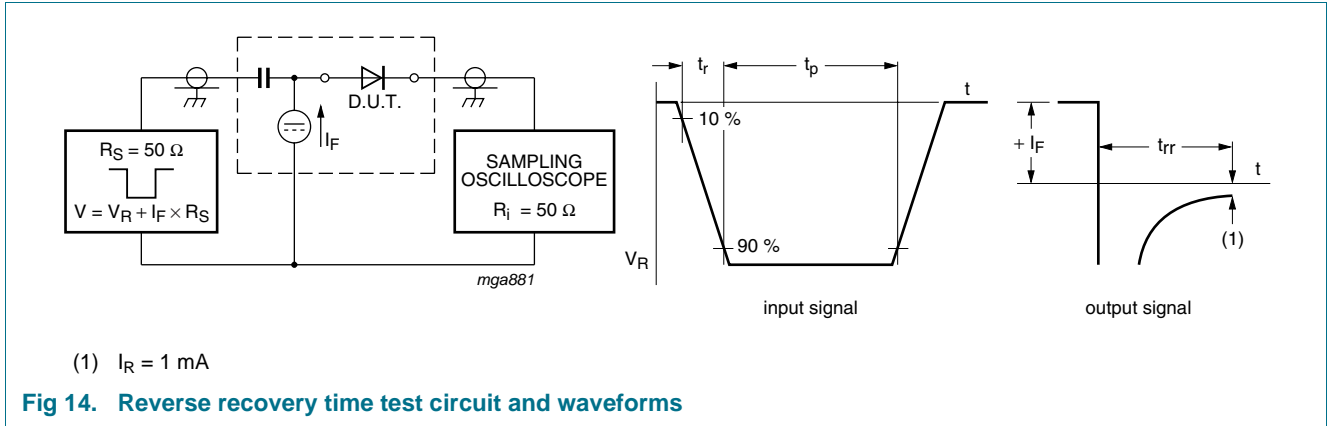
$T_j = 150\text{ °C}$

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 13. Average forward current as a function of solder point temperature; typical values**



**8. Test information**

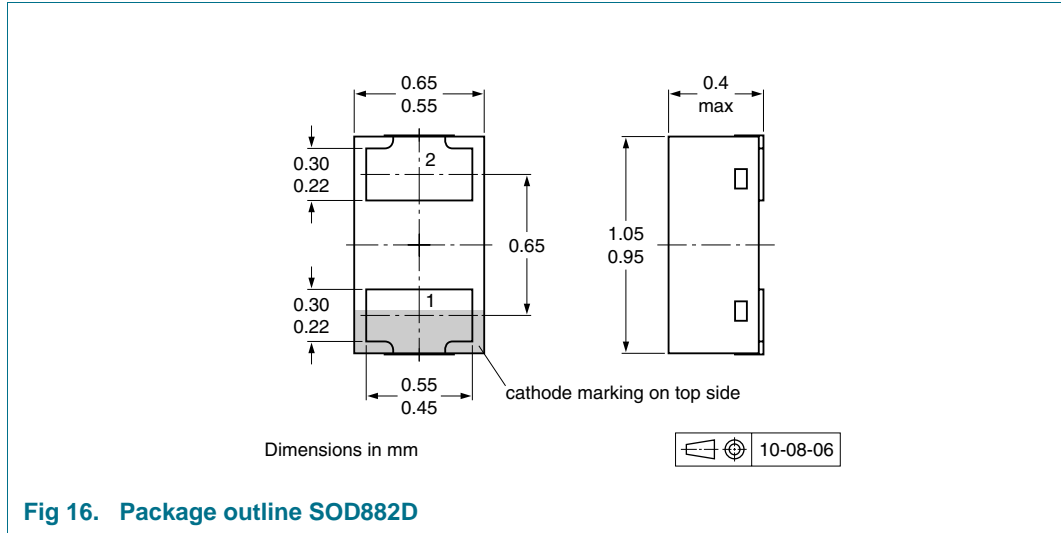


The current ratings for the typical waveforms as shown in [Figure 10](#), [11](#), [12](#) and [13](#) are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

**8.1 Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

**9. Package outline**



**10. Packing information**

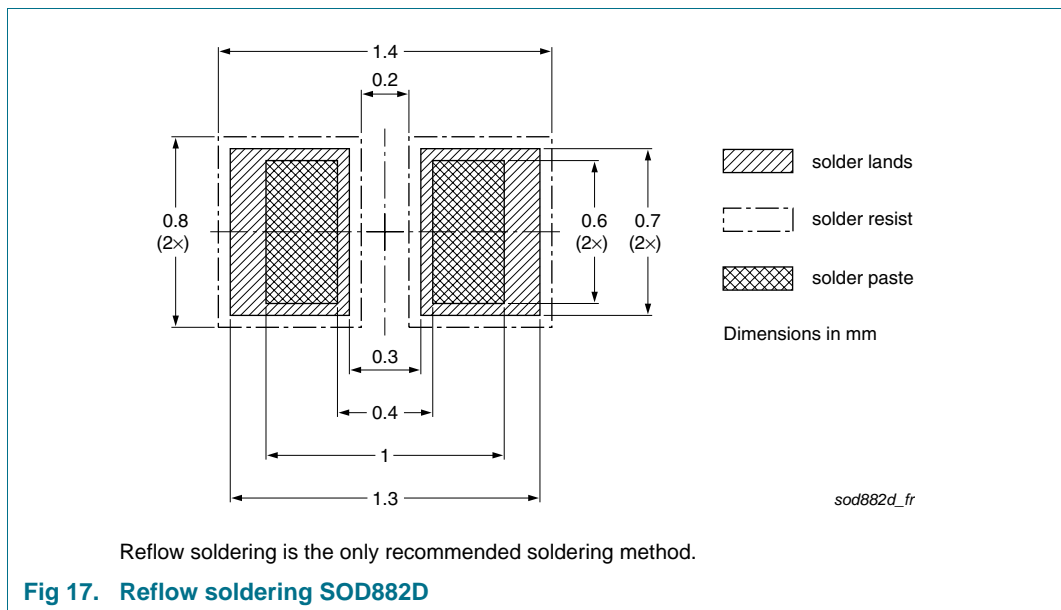
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

| Type number  | Package | Description                    | Packing quantity |
|--------------|---------|--------------------------------|------------------|
| PMEG3002AELD | SOD882D | 2 mm pitch, 8 mm tape and reel | 10000<br>-315    |

[1] For further information and the availability of packing methods, see [Section 14](#).

**11. Soldering**



## 12. Revision history

Table 9. Revision history

| Document ID      | Release date | Data sheet status  | Change notice | Supersedes |
|------------------|--------------|--------------------|---------------|------------|
| PMEG3002AELD v.1 | 20110419     | Product data sheet | -             | -          |

## 13. Legal information

### 13.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

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## 14. Contact information

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For sales office addresses, please send an email to: [salesaddresses@nexperia.com](mailto:salesaddresses@nexperia.com)

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- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
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- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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